VERSION WITH MARKINGS SHOWING CHANGES MADE

Please replace claims 3, 6, 9, 10, 13, 14, and 17-19 with the following amended claims:

3. (Amended) The method of claim 1 ~~or 2~~, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting the conductive pattern to the via conductor.

6. (Amended) The method of claim 4 ~~or 5~~, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting the conductive pattern to the via-conductor.

9. (Amended) The method of claim 7 ~~or 8~~, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting the conductive patterns to the via-conductor.

10. (Amended) The method of ~~any one of claims~~ claim 7 ~~to 9~~, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered substrate; and

connecting the conductive pattern to the via-conductor.

13. (Amended) The method of claim 11 ~~or 12~~, further comprising the step of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting the conductive patterns to the via-hole conductor.

14. (Amended) The method of ~~any one of~~ claim ~~claims~~ 11 ~~to 13~~, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting the conductive pattern to the via-conductor.

17. (Amended) The method of claim 15 ~~or 16~~, wherein the first intaglio and the second intaglio are identical to each other.

18. (Amended) The method of ~~any one of claims~~ claim 15 ~~to 17~~, further comprising the steps of:

forming a first via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting at least one of the first and second conductive patterns to the first via-conductor.

19. (Amended) The method of ~~any one of claims~~ claim 15 ~~to 18~~, further comprising the steps of:

forming a second via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting at least one of said first and second conductive patterns to the second via-conductor.